



# NOTES:

- ALL DIMENSIONS ARE IN MILLIMETERS.
- MD IS THE BALL MATRIX SIZE IN THE "D" DIRECTION, ME IS THE BALL MATRIX SIZE IN THE "E" DIRECTION, AND N IS THE TOTAL NUMBER OF BALLS FOR THE MATRIX SIZE MD X ME AND DOES NOT INCLUDE BALLS FROM ANY DEPOPULATED LOCATIONS. DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5M-1994.
- PRIMARY DATUM C (SEATING PLANE) IS DEFINED BY THE CROWNS OF THE SOLDER BALLS.
- DIMENSION  $b$  IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER IN A PLANE PARALLEL TO DATUM C.
- MARKING SHOWN IS FOR PKG. ORIENTATION PURPOSE ONLY.
- MATERIAL MUST COMPLY WITH BANNED AND RESTRICTED SUBSTANCES SPEC #10-0131.
- ALL DIMENSIONS APPLY TO BOTH LEADED(-) AND PbFREE (+) PKG. CODES.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	-	0.950	-	-	.037	-
A2	0.635	-	0.685	.025	-	.027
b	0.375 BSC			.015 BSC		
D	4.670	-	4.982	.184	-	.196
D1	4.000 BSC			.157 BSC		
E	4.630	-	4.680	.182	-	.184
E1	4.000 BSC			.157 BSC		
e	0.500 BSC			.020 BSC		
c	0.335	-	0.491	.013	-	.019
MD	-	-	9 BALLS	-	-	9 BALLS
ME	-	-	9 BALLS	-	-	9 BALLS
N	75 BALLS			75 BALLS		



TITLE:  
PACKAGE OUTLINE, 75 BALLS  
WLCSP PKG. 0.50mm PITCH, C754A4+1

APPROVAL	DOCUMENT CONTROL NO. 21-0960	REV. A	1/1
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-DRAWING NOT TO SCALE-